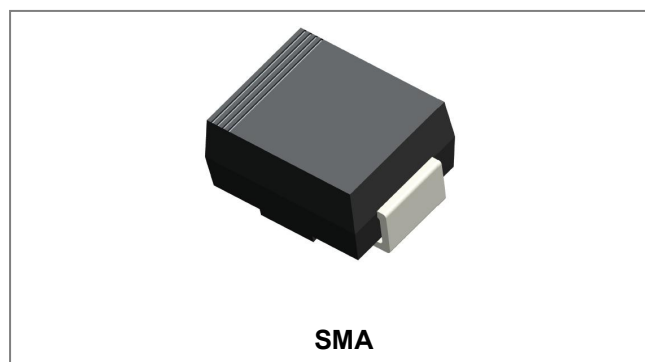


SL12 THRU SL14 LOW VF SURFACE MOUNTSCHOTTKY RECTIFIER



Features

- Schottky Barrier Chip
- Very low forward voltage drop
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: Low Profile Molded plastic
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Color band or cathode Notch
- Mounting Position: Any
- Weight: 0.06grams(approx)

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	SL12	SL13	SL14	Units
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	40	V
Working Peak Reverse Voltage	V _{RWM}				
DC Blocking Voltage	V _R				
Maximum RMS voltage	V _{RMS}	14	21	28	V
Average Rectified Output Current @T _L = 75°C	I _O	1.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30			A
Forward Voltage @ I _O = 1.0 A	V _F	0.38		0.40	V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	0.5 20			mA
Typical Thermal Resistance Junction to Ambient (Note 1)	R _{θJA}	75			K/W
Operating Temperature Range	T _J	-65 to +125			°C
Storage Temperature Range	T _{STG}	-65 to +150			°C

Note: 1. mounted on P.C. Board with 5.0mm² copper pad areas.

- China - Germany - Korea - Singapore - United States •
- <http://www.smc-diodes.com> - sales@smc-diodes.com •

Ratings and Characteristics Curves

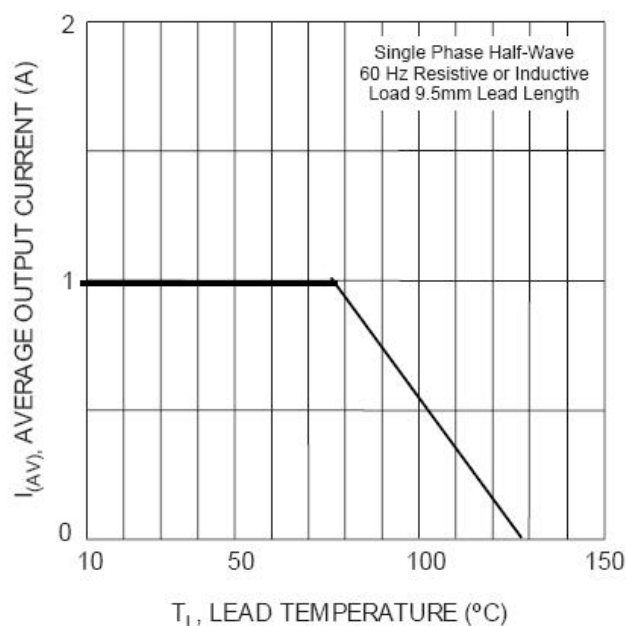


Fig. 1 Forward Current Derating Curve

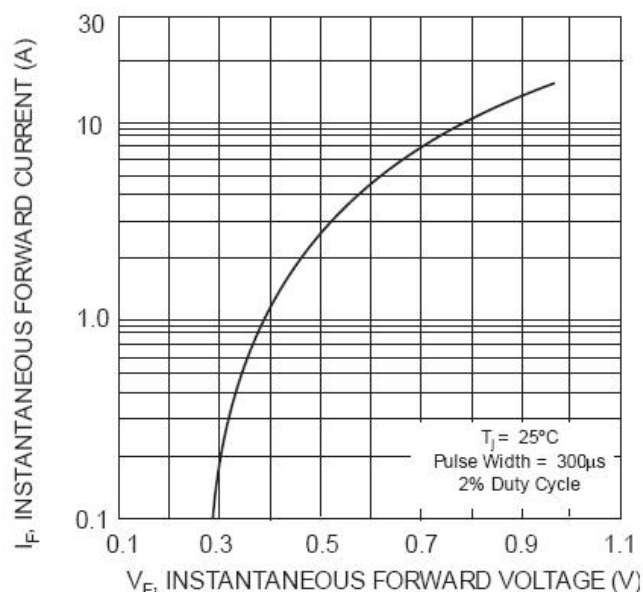


Fig. 2 Typical Forward Voltage Characteristics

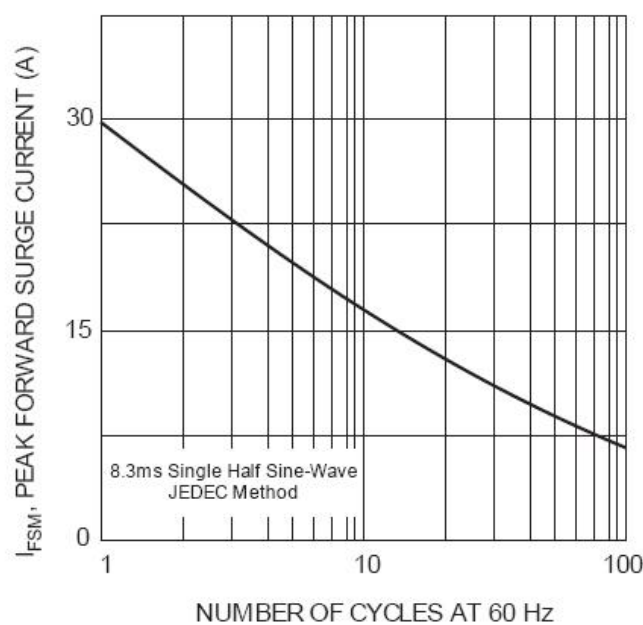


Fig. 3 Peak Forward Surge Current

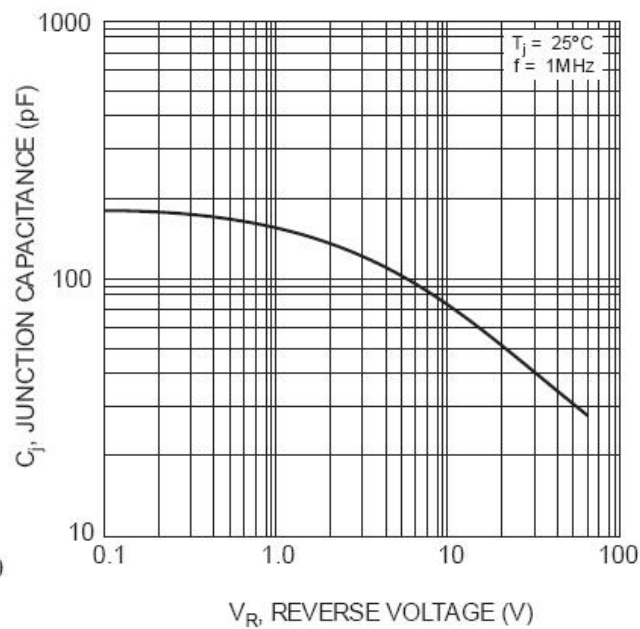
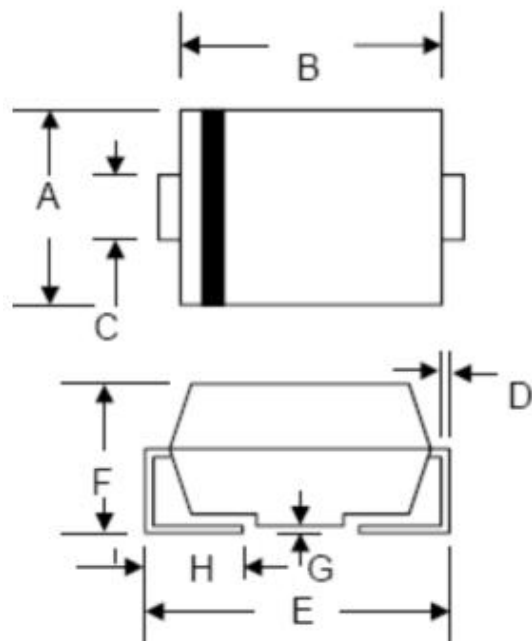


Fig. 4 Typical Junction Capacitance

Mechanical Dimensions SMA



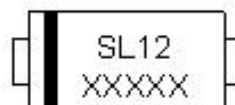
SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.40	2.84	0.094	0.112
B	3.99	4.75	0.157	0.187
C	1.05	1.70	0.041	0.067
D	0.15	0.51	0.006	0.020
E	4.80	5.66	0.189	0.223
F	1.90	2.95	0.075	0.116
G	0.05	0.203	0.002	0.008
H	0.76	1.52	0.030	0.600

Ordering Information

Device	Package	Shipping
SL12 - SL14	SMA (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

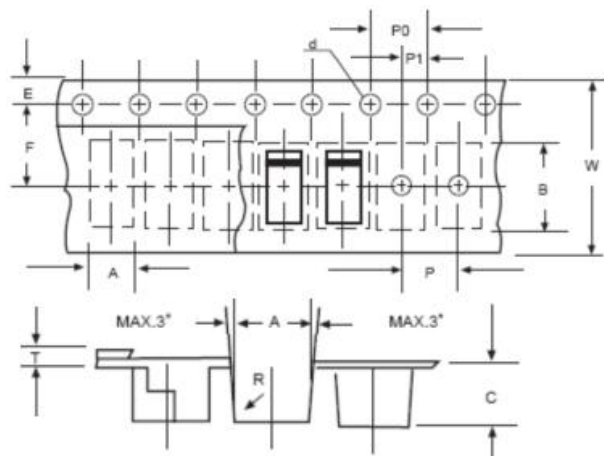


Where XXXXX is YYWWL

SL12 = Part Name
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification SMA



SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20

Technical Data
Data Sheet N0975, Rev. A



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